

#81B
10-7-2
Robertson
and U



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Toshio SHINTANI, et al.

Appln. No.: 09/974,048

Confirmation No.: 7616

Filed: October 11, 2001

Docket No: Q66510

Group Art Unit: 2835

Examiner: Tuan T. DINH

For: CIRCUIT BOARD AND CONNECTION STRUCTURE OF TERMINAL PORTION OF
THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated July 5, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please enter the following amended claims:

1. (Twice Amended) A circuit board comprising:

a terminal portion connected with an external terminal formed in an external circuit, said terminal portion provided with a nickel plating layer and a soldering bump;
wherein a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm ,
wherein said terminal portion further includes a base layer, and a conductive layer disposed between said base layer and said nickel plating layer, wherein a thickness of said base layer comprises polyimide resin.

RECEIVED
OCT 14 2002
TECHNOLOGY CENTER 2800